



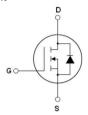
N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- ◆ New technology for high voltage device
- ◆ Low on-resistance and low conduction losses
- ◆ Small package
- ◆ Ultra Low Gate Charge cause lower driving requirements
- ◆ 100% Avalanche Tested
- ◆ ROHS compliant





Schematic diagram

TO-263

Application

- ◆ Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- ◆ Uninterruptible Power Supply (UPS)

V _{DS}	650	V
R _{DS(ON)TYP}	290	mΩ
ID	11.5	А

Package Marking And Ordering Information

Device	Device Package	Marking
MJ65T360D	TO-263	MJ65T360D

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	MJ65T360D	Unit
Drain-Source Voltage (Vcs=0V)	V _D s	650	V
Gate-Source Voltage (V _{DS} =0V) AC (f>1 Hz)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	ID (DC)	11.5	А
Continuous Drain Current at Tc=100°C	ID (DC)	7	Α
Pulsed drain current (Note 1)	IDM (pluse)	46	Α
Maximum Power Dissipation (Tc=25°C)	Po	101	W
Derate above 25°C	PD	0.81	W/°C
Single pulse avalanche energy (Note 2)	Eas	144	mJ
Avalanche current (Note 1)	lar	6	А
Repetitive Avalanche energy, tar limited by T _{jmax} (Note 1)	Ear	0.5	mJ

Parameter	Symbol	MJ65T360D	Unit
Drain Source voltage slope, V _{DS} ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	TJ,TsTG	-55+150	°C





Table 2. Thermal Characteristic

Parameter	Symbol	MJ65T360D	Unit
Thermal Resistance, Junction-to-Case (Maximum)	RthJC	1.24	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	62	°C/W

Table 3. Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BVpss	V _{GS} =0V I _D =250μA	650	-	-	V
Zero Gate Voltage Drain Current (Tc=25°C)	loss	V _{DS} =650V,V _{GS} =0V	-	0.05	1	μΑ
Zero Gate Voltage Drain Current (Tc=125°C)	loss	V _{DS} =650V,V _{GS} =0V	-	-	100	μΑ
Gate-Body Leakage Current	lgss	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	3.5	4	V
Drain-Source On-State Resistance	RDS(ON)	V _{GS} =10V,I _D =7A	-	290	360	mΩ
Dynamic Characteristics						
Input Capacitance	Cies		-	870	-	PF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V F=1.0MHz	-	54	-	PF
Reverse Transfer Capacitance	Crss		-	1.8	-	PF
Total Gate Charge	Qg		-	19	-	nC
Gate-Source Charge	Qgs	V _{DS} =480V,I _D =11.5A V _{GS} =10V	-	6	-	nC
Gate-Drain Charge	Qgd		-	6.5	-	nC
Switching times					ı	
Turn-on Delay Time	t _{d(on)}		-	11	-	nS
Turn-on Rise Time	tr	V _{DD} =380V,I _D =5.5A	-	8	-	nS
Turn-Off Delay Time	t _{d(off)}	R _G =3Ω,V _{GS} =10V	-	58	70	nS
Turn-Off Fall Time	tr		-	9	14	nS
Source- Drain Diode Characteristics					ı	
Source-drain current (Body Diode)	Isp		-	-	11.5	А
Pulsed Source-drain current (Body Diode)	Isdm	- Tc=25°C	-	-	46	А
Forward On Voltage	Vsp	Tj=25°C,Isp=11.5A,Vgs=0V	-	0.9	1.2	V
Reverse Recovery Time	trr		-	220	-	nS
Reverse Recovery Charge	Qrr	T _j =25°C,I _F =5.8A di/dt=100A/µs	-	2.2	-	uC
Peak reverse recovery Current	Irrm		_	19	_	А



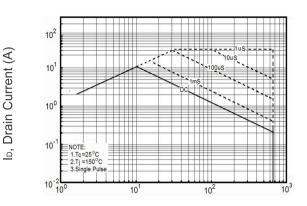




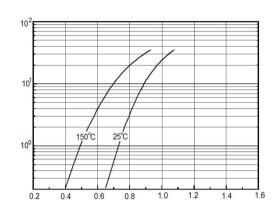
Notes

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- $2.T_j=25^{\circ}C,V_{DD}=50V,V_{G}=10V,R_{G}=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

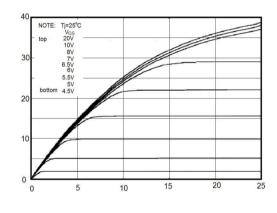


lor, Reverse Drain Current(A)



V_{DS}, Drain-Source Voltage (V)

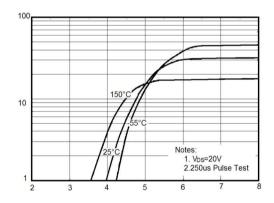
Figure 1 Safe operating area



lb, Drain Current (A)

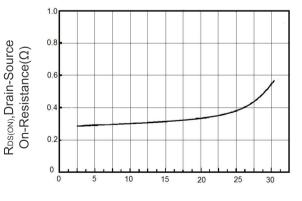
Vsp,Source-Drain Voltage(V)

Figure 2 Source-Drain Diode Forward Voltage



V_{DS}(V)

Figure 3 Output characteristics



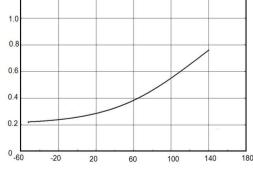
RDS(ON), Drain-Source On-Resistance(Ω)

Figure 4 Transfer characteristics

V_{GS}, Gate-Source Voltage (V)

ID, Drain Current (A)

Figure 5 Static drain-source on resistance



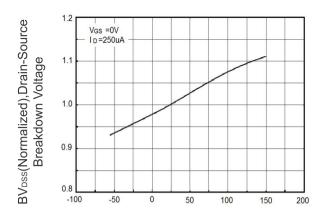
T_J, Junction Temperature (°C)

Figure 6 RDS(ON) vs Junction Temperature

lo, Drain Current (A)

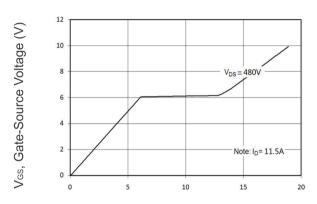
Capacitances(pF)





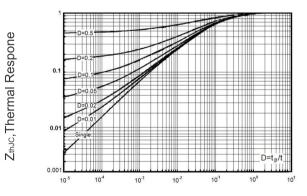
T_J, Junction Temperature (°C)

Figure 7 BVDSS vs Junction Temperature



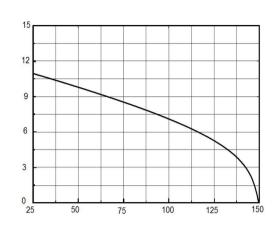
Q_G,Total Gate Charge(nC)

Figure 9 Gate charge waveforms



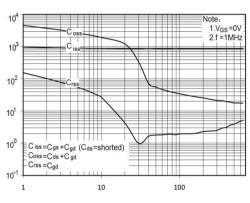
tp,Square Wave Pulse(S)

Figure 11 Transient Thermal Impedance



Tc, Case Temperature (°C)

Figure 8 Maximum ID vs Junction Temperature



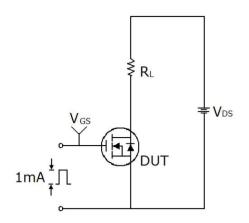
V_{DS}, Drain-Source Voltage (V)

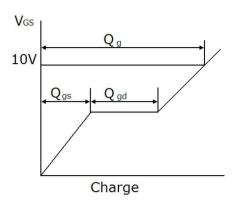
Figure 10 Capacitance



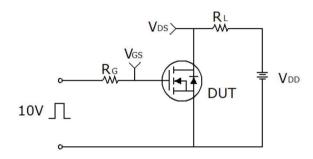


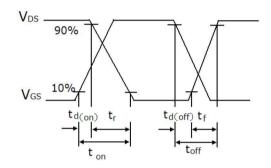
Test circuit



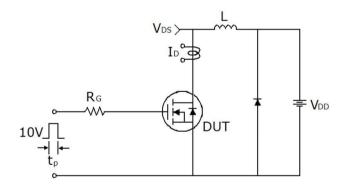


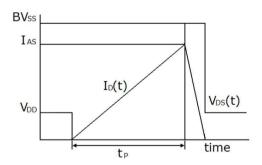
Gate charge test circuit & Waveform





Switch Time Test Circuit



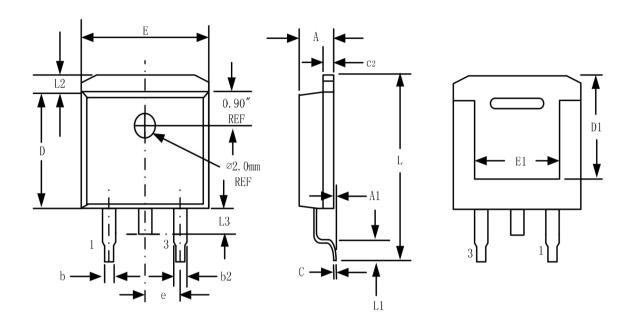


Unclamped Inductive Switching Test Circuit & Waveforms



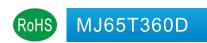


TO-263-3L Package Information



Symbol	Dimensions	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.		
А	4.32	4.57	0.170	0.180		
A1	-	0.25		0.010		
b	0.71	0.94	0.028	0.037		
b2	1.15	1.40	0.045	0.055		
С	0.46	0.61	0.018	0.024		
c2	1.22	1.40	0.048	0.055		
D	8.89	9.40	0.350	0.370		
D1	8.01	8.23	0.315	0.324		
E	10.04	10.28	0.395	0.405		
E1	7.88	8.08	0.310	0.318		
е	2.54	2.54 BSC		BSC		
L	14.73	15.75	0.580	0.620		
L1	2.29	2.79	0.090	0.110		
L2	1.15	1.39	0.045	0.055		
L3	1.27	1.77	0.050	0.070		





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